

SURFACE MOUNT HIGH EFFICIENCY RECTIFIER

Features

- ◆ Glass passivated device
- ◆ Ideal for surface mouted applications
- ◆ Low reverse leakage
- ◆ Metallurgically bonded construction
- ◆ High temperature soldering guaranteed:
250°C/10 seconds, 0.375" (9.5mm) lead length,
5 lbs. (2.3kg) tension

Mechanical Data

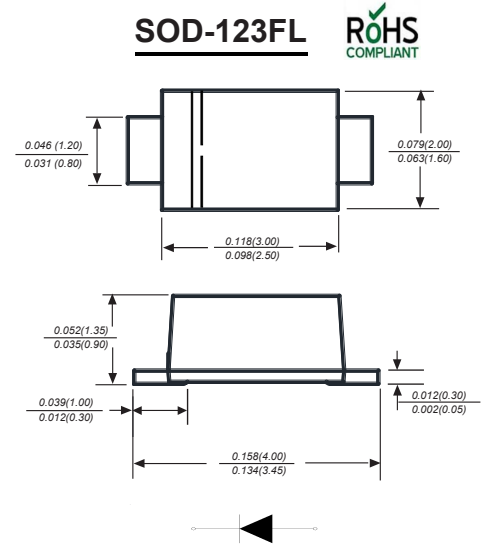
Case : JEDEC SOD-123FL Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0007 ounce, 0.02 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	US2AW	US2BW	US2DW	US2EW	US2GW	US2JW	US2KW	US2MW	UNITS
Marking Code		2U1	2U2	2U3	2U4	2U5	2U6	2U7	2U8	
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	300	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	210	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	300	400	600	800	1000	V
Maximum average forward rectified current at TL=65°C	I _(AV)	2.0								A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50								A
Maximum instantaneous forward voltage at 2.0A	V _F	1.0			1.30		1.70			V
Maximum DC reverse current at rated DC blocking voltage T _A =25°C T _A =125°C	I _R	5.0 100.0								μA
Maximum reverse recovery time (NOTE 1)	t _{rr}	50					75			ns
Typical junction capacitance (NOTE 2)	C _J	15.0								pF
Typical thermal resistance	R _{θJA}	90.0								°C/W
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150								°C

Note: 1. Measured with $I_F=0.5\text{A}$, $I_R=1\text{A}$, $I_{rr}=0.25\text{A}$.

Ratings And Characteristic Curves

Fig.1 Maximum Average Forward Current Rating

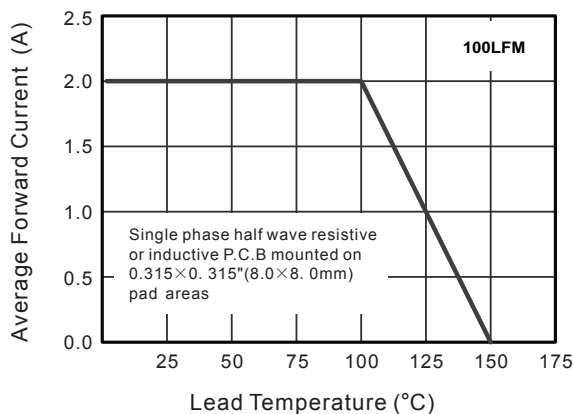


Fig.2 Typical Reverse Characteristics

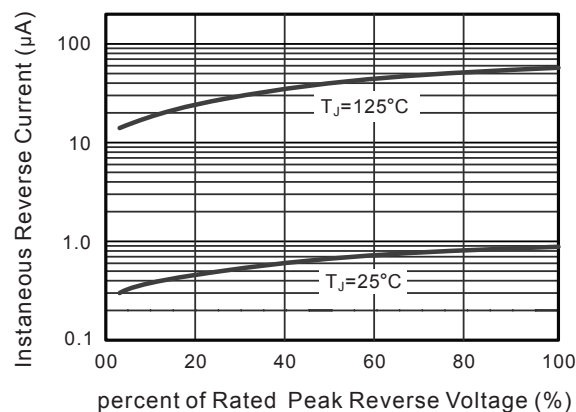


Fig.3 Typical Forward Characteristics

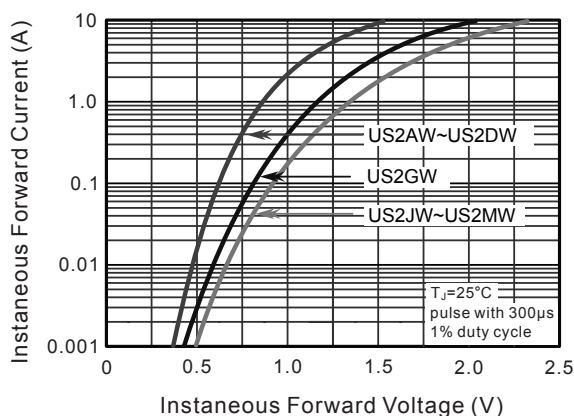


Fig.4 Typical Junction Capacitance

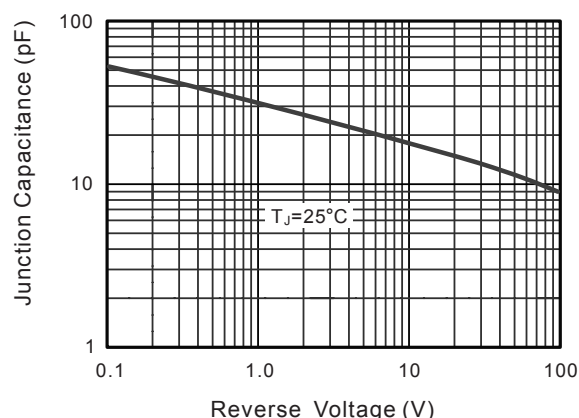


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

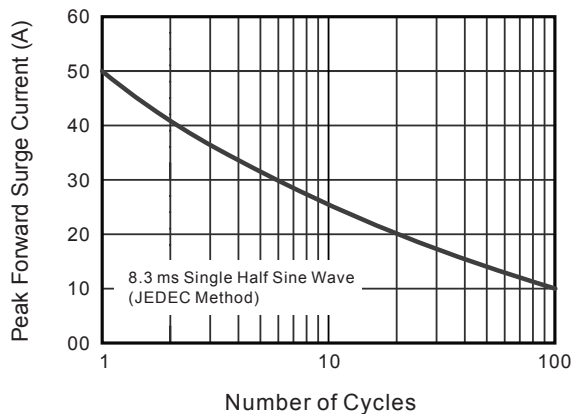
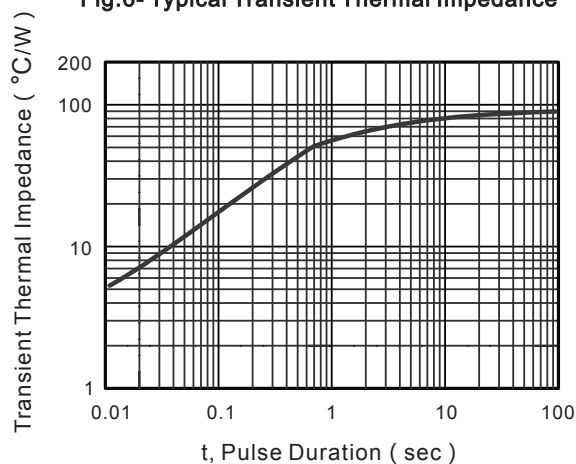


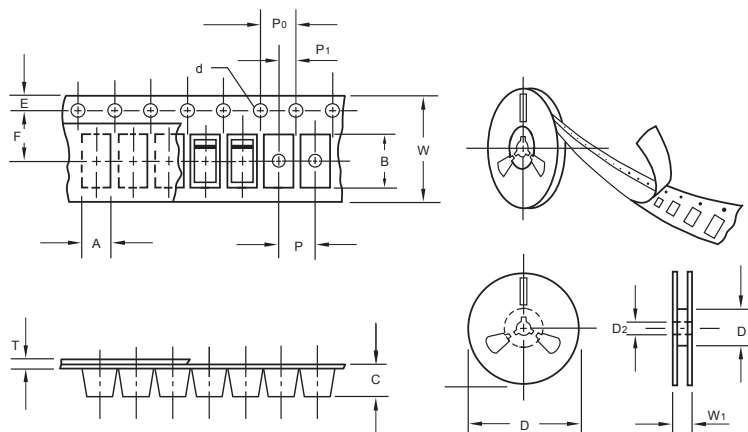
Fig.6- Typical Transient Thermal Impedance



The curve above is for reference only.

Packing information

unit:mm



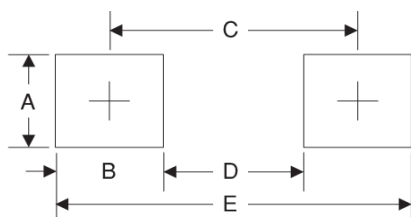
Item	Symbol	Tolerance	SOD-123FL
Carrier width	A	0.1	2.1
Carrier length	B	0.1	4.0
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.55
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	50.0
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	8.15
Reel width	W ₁	1.0	10.5

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-123FL	7"	3,000	4.0	45,000	210*208*203	178	430*430*235	180,000	9.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.047
B	1.2	0.047
C	3.2	0.126
D	2	0.079
E	4.4	0.173